Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	59965	glass near2 (powder particulat$4 particl$4 partical fragment piece)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:39
L5	1985135	resin epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:39
L6	4049935	throughhole or through adj hole or via damascene trench channel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:39
L7	191	L4 with L5 same L6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:39
L8	96	L7 and (@ad < "19980601")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:59
L9	552982	(silicon si! semiconduct$4) near2 (wafer substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:44
L10	6	8 and 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:44
L11	19	7 and 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:45
L12	1	7 same 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:49
L13	2	"6194024".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:51

L14	2	"4840923".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:51
L15	594	backpolish$4 back-polish$4 back adj polish$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:56
L16	1454	backgrind$4 back-grind$4 back adj grind$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:56
L17	16086	expos$4 near2 (via throughhole through adj hole through-hole chip near through throughchip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:58
L18	423	expos$4 near2 (via throughhole through adj hole through-hole chip near through throughchip) with (back backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:59
L20	0	18 with 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:58
L21	0	18 same 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:58
L22	4	18 and 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 21:58
L23	0	22 and (@ad < "19980601")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:00
L24	55	16 with (via throughhole through adj hole through-hole chip near through throughchip) with (back backside)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:02

L25	22	24 and (@ad < "19980601")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:02
L26	59	16 with (via throughole through adj hole through-hole chip near through throughchip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:03
L27	23	26 and (@ad < "19980601")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:03
L28	0	27 not 26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:02
L29	0	16 with (chip near through throughchip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:03
L30	2	16 same (chip near through throughchip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:03
L31	36	16 and (chip near through throughchip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:04
L32	4	31 and (@ad < "19980601")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:04
L33	2	15 and (chip near through throughchip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:06
L34	2	"6534879".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/02 22:06

L35	849	((438/977) or (438/928)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/02 22:07
L36	3726	((438/637) or (438/640) or (438/675) or (438/977) or (438/928)).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/02 22:08